

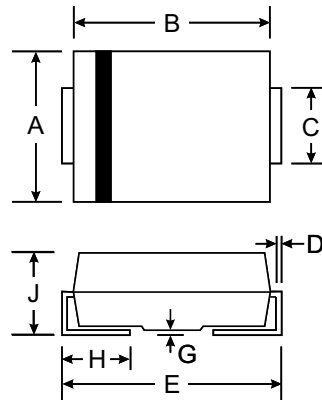
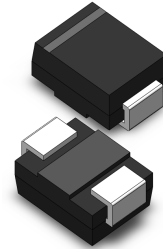
VOLTAGE RANGE: 100 - 200V
CURRENT: 2.0 A

Features

- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Low Forward Voltage Drop, High Efficiency
- Low Power Loss
- Super-Fast Recovery Time
- Plastic Case Material has UL Flammability Classification Rating 94V-O

Mechanical Data

- Case: SMB(DO-214AA) , Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.093 grams (approx.)



SMB(DO-214AA)		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.70
C	1.91	2.21
D	0.15	0.31
E	5.00	5.59
G	0.10	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	ESH2B	ESH2C	ESH2D	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	100	150	200	V
Working Peak Reverse Voltage	V _{RWM}				
DC Blocking Voltage	V _R				
RMS Reverse Voltage	V _{R(RMS)}	70	105	140	V
Average Rectified Output Current @T _L = 75°C	I _O	2.0			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50			A
Forward Voltage @I _F = 2.0A	V _{FM}	0.95			V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	5.0 200			μA
Reverse Recovery Time (Note 1)	t _{rr}	35			nS
Typical Junction Capacitance (Note 2)	C _j	62			pF
Typical Thermal Resistance	R _{θJL}	40			K/W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +150			°C

Note: 1. Measured with I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A,
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.



FIG. 1- FORWARD CURRENT DERATING CURVE

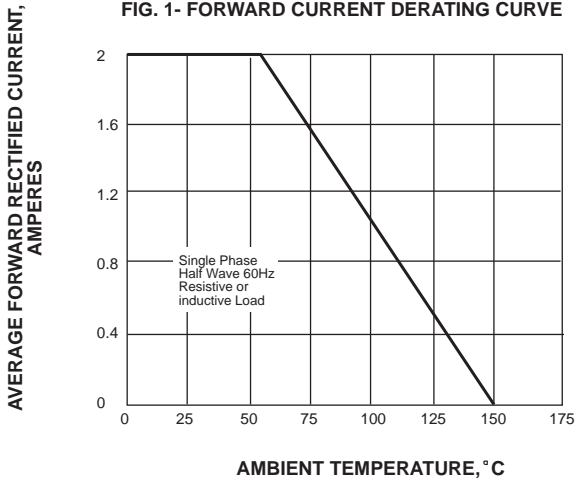


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

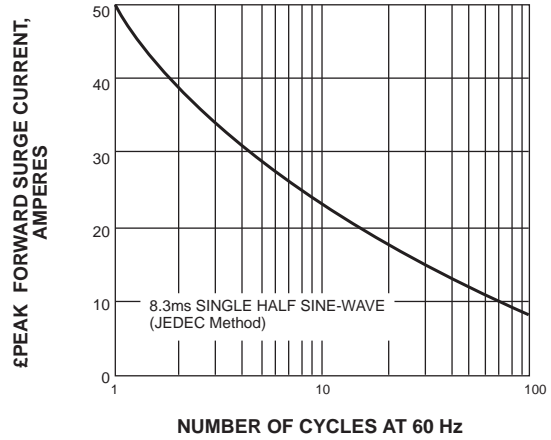


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

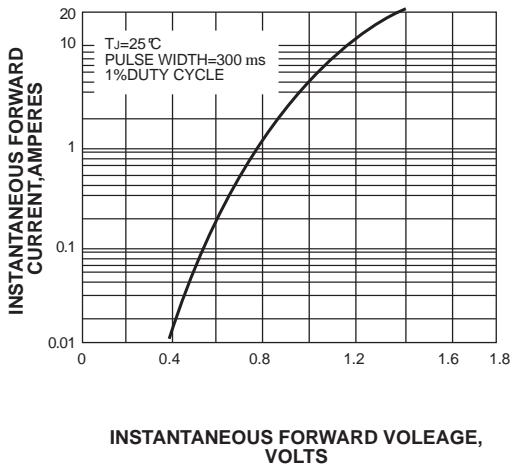


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

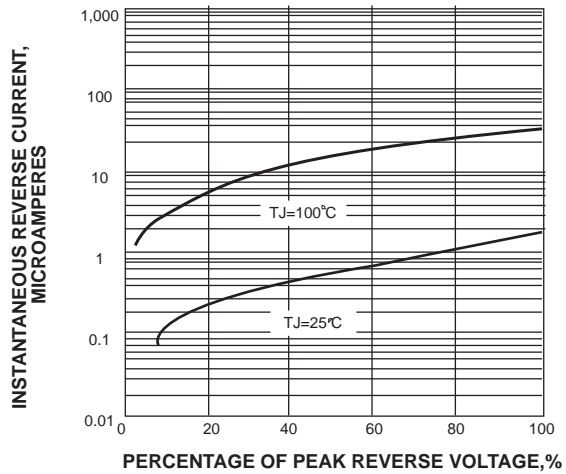


FIG. 5-TYPICAL JUNCTION CAPACITANCE

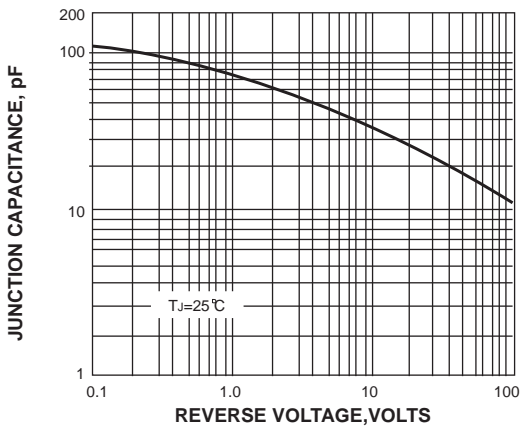


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE

